

EAST: (10625010 non-metal test pads.wsp:1)

File View List Tools Window Help

125: (3668559) (organic polymer\$6 polyimid\$4 co adj) polyme\$4 copolym
126: (2353236) (polymer\$6 polyimid\$4 co adj) polyme\$4 copolyme\$4 cou
127: (3103983) 26 18
128: (23047) (bond heel bump) adj (pad)
129: (421 27 adj) 28
130: (191 29 and 18
131: (101 30 and 1
132: (10 29 and 1
133: (1748531) adhe\$6
134: (291 29 and 33
135: (281 34 and 24
136: (281 35 and 27
137: (2061) prob\$4 adj pad
138: (121 27 near 2 37
139: (151 15 and 24
140: (1209) 28 near 8 33
141: (71 40 same 1
142: (1576885) (multi\$4 multiplici\$3 plural\$4 dual) adj (layer film) multi
143: (1981 28 near 42
144: (1221 43 and 6
145: (2000) 33 with 28
146: (15) 44 and 45
147: (151503) die
148: (1901 8 15 30 36 48
149: (199) 47 and 48

43 and 6

June 2005

	U	I	Inventor	Document	Issu	P	Title	Current	Current	K	Retrie	S	C	P	Image	On	P
1			Yin, Leung Ha	US 200300	2003	12	Wire bonded microelectronic device s	438/10	257/E21.51								US 20030
2			Yu, Chen-H	US 670328	2004	8	Metal bond pad for low-k inter metal di	438/40	257/780								US 670328
3			Martin, L Se	US 200400	2004	2	USE OF AMORPHOUS ALUMINUM OXIDE ON	257/29	257/E21.0								US 20040
4			Akhan, Mo	US 200400	2004	16	Edge-sealed substrates and methods f	438/12									US 20040
5			Fehr, Gera	US 200400	2004	9	Method for stack-packaging integrate	438/10	257/E25.0								US 20040
6			Akram, Sai	US 200400	2004	15	Semiconductor package with stacked	438/10	257/E21.70								US 20040
7			Downey, Su	US 200400	2004	6	Semiconductor device having a wire bo	257/75	257/762								US 20040
8			Gleason, Jef	US 200400	2004	14	Nickel bonding cap over copper metaliz	257/45									US 20040
9			Batra, Shub	US 200302	2003	13	Method and structures for reduced par	257/48	257/E23.0								US 20030
10			Batra, Shub	US 200302	2003	12	Method and structures for reduced par	257/75	257/E23.0								US 20030

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